

L Number	Hits	Search Text	DB	Time stamp
1	0	257/666.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/29 23:46
2	3122	257/666.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/29 23:47
3	55	257/666.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:16
4	157	257/778.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/29 23:59
5	16	("5471027" "5608262" "5708296" "5757074" "5784261" "5812380" "5883425" "5907477" "5962133" "5981314" "6061248" "6093972" "6108210" "6218730" "6235996" "6241145").PN.	USPAT	2002/12/29 23:56
7	438		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:28
8	370		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:09
9	0	257778.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:17
10	157	257/778.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:19
11	105	(257/778.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))) and (substrate and (encapsulat\$3 or mold\$3 or resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:17
12	42	257/787.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:39
13	0	20020086500.URPN.	USPAT	2002/12/30 00:20
14	11	257/796.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:25
15	64	257/793.ccls. and (chips or dies)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:28

16	36430	substrate and (epox\$3 near (encapsulat\$3 or mold\$3 or resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:29
17	440	((substrate and (epox\$3 near (encapsulat\$3 or mold\$3 or resin))) and ((first and second) near (chip\$2 or die\$2)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:31
18	247	((substrate and (epox\$3 near (encapsulat\$3 or mold\$3 or resin))) and ((first and second) near (chip\$2 or die\$2))) and ball\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:31
19	15	257/722.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:41
20	130	257/723.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:47
21	93	257/724.ccls. and (ball\$2 and (capacitor or resistor or inductor or passive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/30 00:47